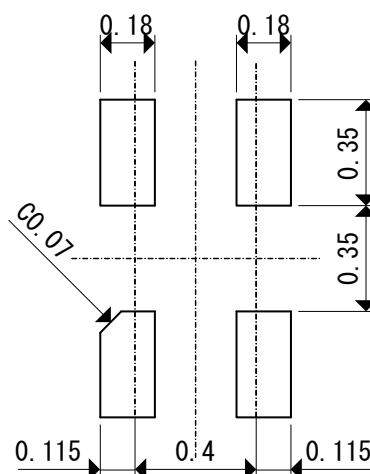
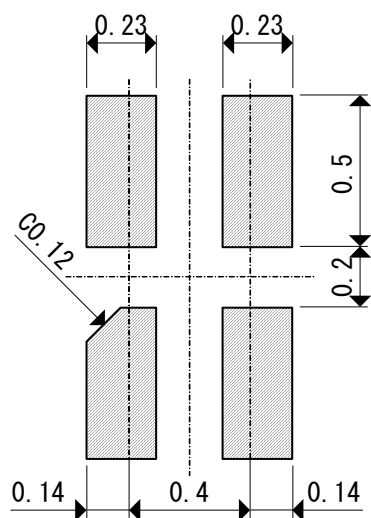


■Packaging Information

Technical drawing of a mechanical part. The drawing includes the following dimensions and features:

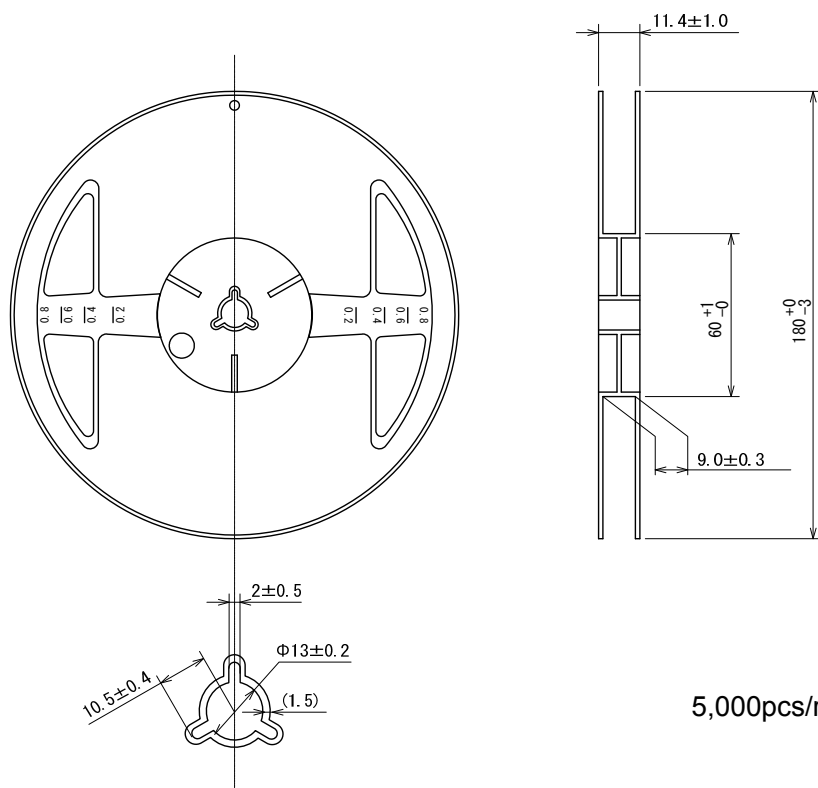
- Overall width: 0.75 ± 0.05
- Overall height: 0.95 ± 0.05
- A circular feature (pin indent) is located in the bottom-left corner, indicated by an arrow and the label "pin INDENT".
- A dimension of 0.38 ± 0.03 is shown on the left side, corresponding to the height of the pin indent.
- A dimension of 0.18 ± 0.0 is shown at the top, corresponding to the width of the pin indent.
- A dimension of 0.07 is shown on the left side, corresponding to the radius of the pin indent.
- A dimension of 0.2 ± 0.05 is shown at the bottom, corresponding to the height of the pin indent.
- A dimension of 0.325 ± 0.05 is shown at the bottom, corresponding to the width of the pin indent.
- A dimension of 0.4 is shown at the bottom, corresponding to the width of the pin indent.

Reference metal mask design



Taping Specifications

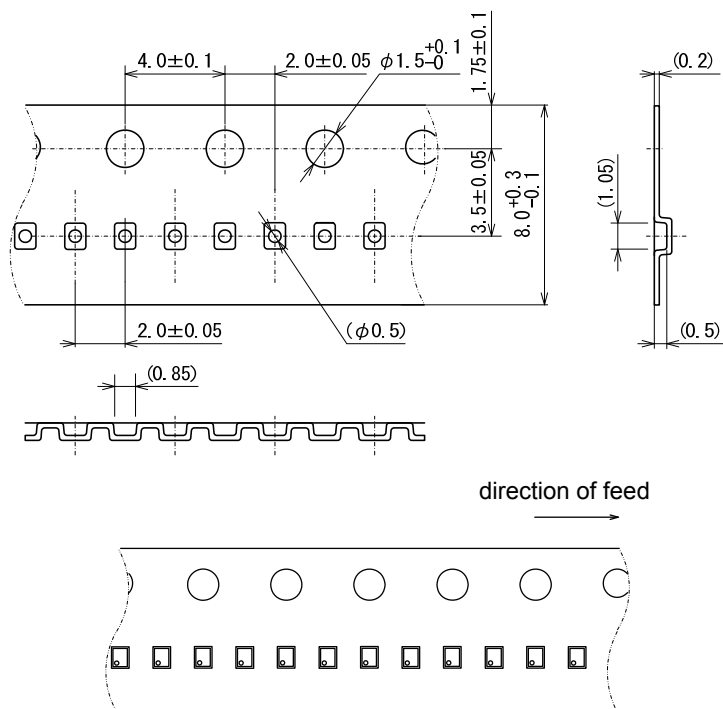
●USPN-4B02 Reel



Unit: mm

5,000pcs/reel

●Taping Specifications



R Type :[Device orientation : Right]

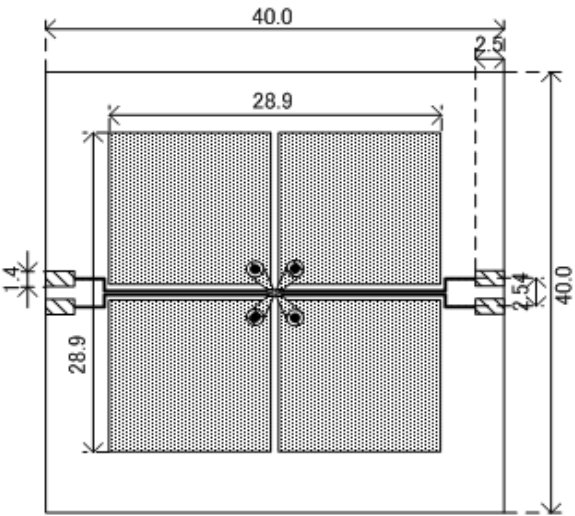
Standard feed

● USPN-4B02 Power Dissipation

Power dissipation data for the USPN-4B02 is shown in this page.
 The value of power dissipation varies with the mount board conditions.
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
 Copper (Cu) traces occupy 50% of the front and 50% of the back.
 The copper area is divided into four block,
 one block is 12.5% of total.
 The USPN-4 package has for terminals.
 Each terminal connects one copper block in the front
 and one in the back.
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

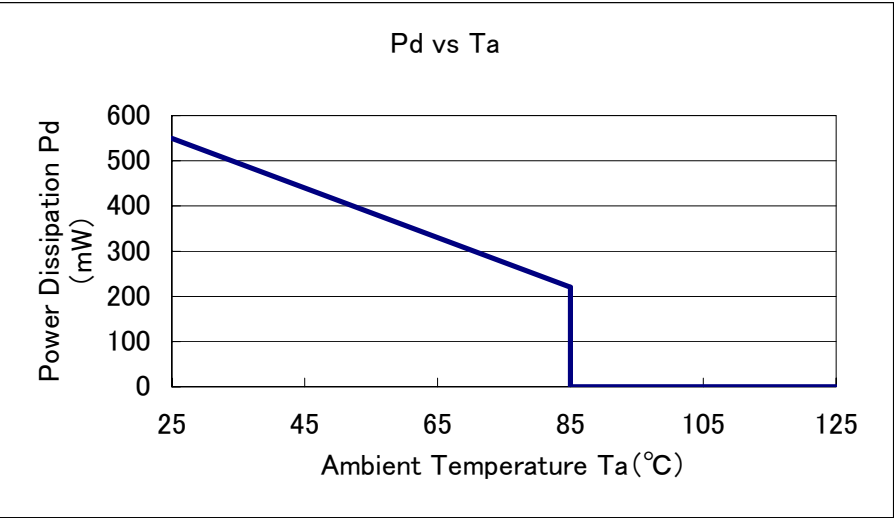


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (T_j max = 125°C)

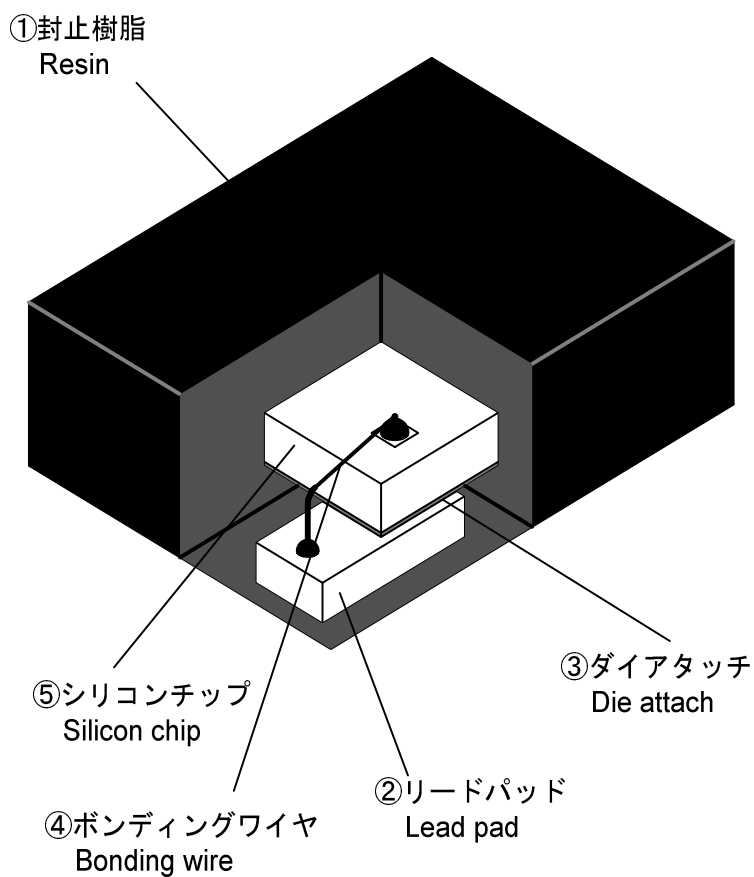
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	550	181.82
85	220	



USPN-4B02構造図

USPN-4B02 Perspective

RoHS対応品
RoHS Compliance



項 目 item		材 料 material	備 考 Note
①	封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードパッド Lead pad	ニッケル Nickel	
	端子処理 Outer pad plating	Auメッキ Gold plating	
③	ダイアタッチ Die attach	ダイアタッチフィルム Die attach film	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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